# PROCEEDINGS OF SPIE

# Components and Packaging for Laser Systems VIII

Alexei L. Glebov Paul O. Leisher Editors

22-27 January 2022 San Francisco, California, United States

20-24 February 2022 ONLINE

Sponsored and Published by SPIF

**Volume 11982** 

Proceedings of SPIE 0277-786X, V. 11982

SPIE is an international society advancing an interdisciplinary approach to the science and application of light.

Components and Packaging for Laser Systems VIII, edited by Alexei L. Glebov, Paul O. Leisher, Proc. of SPIE Vol. 11982, 1198201 ⋅ © 2022 SPIE ⋅ 0277-786X ⋅ doi: 10.1117/12.2635348

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Please use the following format to cite material from these proceedings:

Author(s), "Title of Paper," in Components and Packaging for Laser Systems VIII, edited by Alexei L. Glebov, Paul O. Leisher, Proc. of SPIE 11982, Seven-digit Article CID Number (DD/MM/YYYY); (DOI URL).

ISSN: 0277-786X

ISSN: 1996-756X (electronic)

ISBN: 9781510648357

ISBN: 9781510648364 (electronic)

Published by

SPIE

P.O. Box 10, Bellingham, Washington 98227-0010 USA Telephone +1 360 676 3290 (Pacific Time)

SPIE.org

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